

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPD70N10S3-12	**Issued**	06. May 2021
MA#	MA001390132		
Package	PG-TO252-3-11	**Weight***	374.32 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	5.833	1.56	1.56	15584	15584
leadframe	inorganic material	phosphorus	7723-14-0	0.065	0.02		173	
	non noble metal	iron	7439-89-6	0.215	0.06		575	
	non noble metal	copper	7440-50-8	215.017	57.44	57.52	574426	575174
wire	non noble metal	aluminium	7429-90-5	4.819	1.29	1.29	12874	12874
encapsulation	inorganic material	zincoxide	1314-13-2	1.206	0.32		3221	
	miscellaneous	miscellaneous	-	6.029	1.61		16107	
	plastics	epoxy resin	-	18.087	4.83		48321	
	inorganic material	silicondioxide	60676-86-0	95.260	25.45	32.21	254491	322140
leadfinish	non noble metal	tin	7440-31-5	3.740	1.00	1.00	9992	9992
plating	inorganic material	phosphorus	7723-14-0	0.000			1	
	non noble metal	nickel	7440-02-0	0.091	0.02	0.02	243	244
solder	non noble metal	tin	7440-31-5	0.095	0.03		254	
	noble metal	silver	7440-22-4	0.119	0.03		317	
	non noble metal	lead	7439-92-1	4.537	1.21	1.27	12122	12693
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			15	
	non noble metal	iron	7439-89-6	0.019	0.01		51	
	non noble metal	copper	7440-50-8	19.177	5.12	5.13	51233	51299
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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